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STS4C3F60L

N-channel 60V - 0.045 Ω - 4A SO-8
Complementary pair STripFET™ Power MOSFET

General features

| Type | V _{DSS} | R _{DS(on)} | I _D |
|-----------------------|------------------|---------------------|----------------|
| STS4C3F60L(N-channel) | 60V | <0.056 Ω | 4A |
| STS4C3F60L(P-channel) | 60V | <0.120 Ω | 3A |

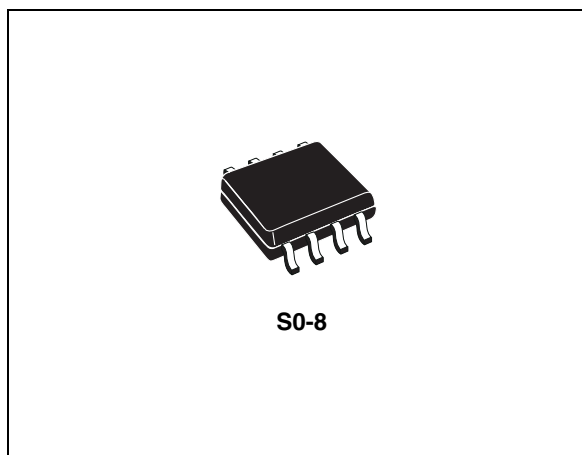
- Standard outline for easy automated surface mount assembly
- Low threshold drive

Description

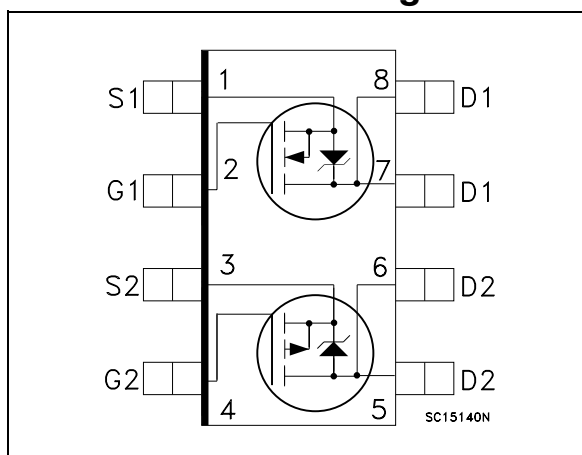
This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Applications

- Switching application



Internal schematic diagram



Order codes

| Part number | Marking | Package | Packaging |
|-------------|----------|---------|-------------|
| STS4C3F60L | S4C3F60L | SO-8 | Tape & reel |

Contents

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1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | | Unit |
|--------------------|--|------------|-----------|------------------|
| | | N-channel | P-channel | |
| V_{DS} | Drain-source voltage ($v_{gs} = 0$) | 60 | | V |
| V_{GS} | Gate- source voltage | ± 16 | | V |
| I_D | Drain current (continuous) at $T_C = 25^\circ\text{C}$ | 4 | 3 | A |
| I_D | Drain current (continuous) at $T_C = 100^\circ\text{C}$ | 2.5 | 1.9 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 16 | 12 | A |
| P_{TOT} | Total dissipation at $T_C = 25^\circ\text{C}$ | 2 | | W |
| T_{stg} T_j | Storage temperature Max. operating junction temperature | -55 to 150 | | $^\circ\text{C}$ |

1. Pulse width limited by safe operating area

Note: For the P-CHANNEL MOSFET actual polarity of voltages and current has to be reversed

Table 2. Thermal data

| | | | |
|-------------------|-------------------------------------|------|--------------------|
| $R_{thj-a}^{(1)}$ | Thermal resistance junction-ambient | 62.5 | $^\circ\text{C/W}$ |
|-------------------|-------------------------------------|------|--------------------|

1. When mounted on 1 in² pad of 2 oz. copper, $t \leq 10$ sec.

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 3. On/off states

| Symbol | Parameter | Test conditions | | Min. | Typ. | Max. | Unit |
|---------------------------|---|--|------|------|-------|-----------|----------|
| $V_{(BR)DS}$ _s | Drain-source Breakdown voltage | $I_D = 250 \mu A, V_{GS} = 0$ | n-ch | 60 | | | V |
| | | | p-ch | 60 | | | V |
| I_{DSS} | Zero gate voltage Drain current ($V_{GS} = 0$) | $V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}, T_C = 125^{\circ}C$ | n-ch | | | 1 | μA |
| | | | p-ch | | | 10 | μA |
| I_{GSS} | Gate-body leakage current ($V_{DS} = 0$) | $V_{GS} = \pm 16V$ | n-ch | | | ± 100 | nA |
| | | | p-ch | | | ± 100 | |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | n-ch | 1 | | | V |
| | | | p-ch | 1.5 | | | V |
| $R_{DS(on)}$ | Static drain-source on resistance | $V_{GS} = 10V, I_D = 2A$ $V_{GS} = 10V, I_D = 1.5A$ $V_{GS} = 10V, I_D = 2A$ $V_{GS} = 10V, I_D = 1.5A$ | n-ch | | 0.045 | 0.055 | Ω |
| | | | p-ch | | 0.100 | 0.120 | Ω |
| | | | n-ch | | 0.050 | 0.065 | Ω |
| | | | p-ch | | 0.130 | 0.160 | Ω |

Table 4. Dynamic

| Symbol | Parameter | Test conditions | | Min. | Typ. | Max. | Unit |
|--------------|---------------------------------|---|------|------|------|------|------|
| g_{fs} (1) | Forward transconductance | $V_{DS} = 30 V, I_D = 2A$ $V_{DS} = 10 V, I_D = 3A$ | n-ch | | 7 | | S |
| | | | p-ch | | 7.2 | | S |
| C_{iss} | Input capacitance | | n-ch | | 1030 | | pF |
| | | | p-ch | | 630 | | pF |
| C_{oss} | Output capacitance | $V_{DS} = 25V, f = 1 \text{ MHz},$ $V_{GS} = 0$ | n-ch | | 140 | | pF |
| | | | p-ch | | 121 | | pF |
| C_{rss} | Reverse transfer capacitance | | n-ch | | 40 | | pF |
| | | | p-ch | | 49 | | pF |
| Q_g | Total gate charge | N-channel $V_{DD} = 48V, I_D = 4A$ $V_{GS} = 4.5V$ | n-ch | | 15 | 20.4 | nC |
| | | | p-ch | | 11.6 | 15.7 | nC |
| Q_{gs} | Gate-source charge | P-channel $V_{DD} = 48V, I_D = 3A$ | n-ch | | 4 | | nC |
| | | | p-ch | | 4.5 | | nC |
| Q_{gd} | Gate-drain charge | $V_{GS} = 4.5V$ (see Figure 26) | n-ch | | 4 | | nC |
| | | | p-ch | | 4.7 | | nC |

1. Pulsed: Pulse duration = 300 μs , duty cycle 1.5.

Table 5. Switching times

| Symbol | Parameter | Test conditions | | Min. | Typ. | Max. | Unit |
|-----------------------|----------------------------------|---|------|------|------|------|------|
| $t_{d(on)}$ t_r | Turn-on delay time Rise time | N-channel $V_{DD} = 30\text{ V}$, $I_D = 2\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ | n-ch | | 15 | | ns |
| | | | p-ch | | 124 | | ns |
| | | P-channel $V_{DD} = 30\text{ V}$, $I_D = 1.5\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ (see Figure 25) | n-ch | | 28 | | ns |
| | | | p-ch | | 54 | | ns |
| $t_{d(off)}$ t_f | Turn-off delay time Fall time | N-channel $V_{DD} = 30\text{ V}$, $I_D = 2\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ | n-ch | | 45 | | ns |
| | | | p-ch | | 39 | | ns |
| | | P-channel $V_{DD} = 30\text{ V}$, $I_D = 1.5\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ (see Figure 25) | n-ch | | 10 | | ns |
| | | | p-ch | | 14.5 | | ns |

Table 6. Source drain diode

| Symbol | Parameter | Test conditions | | Min. | Typ. | Max | Unit |
|-----------------|-------------------------------|---|------|------|------|-----|------|
| I_{SD} | Source-drain current | | n-ch | | | 4 | A |
| | | | p-ch | | | 3 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | n-ch | | | 16 | A |
| | | | p-ch | | | 12 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 4\text{ A}$, $V_{GS} = 0$ $I_{SD} = 3\text{ A}$, $V_{GS} = 0$ | n-ch | | | 1.2 | V |
| | | | p-ch | | | 1.2 | V |
| t_{rr} | Reverse recovery time | N-channel $I_{SD} = 4\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 20\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ | n-ch | | 85 | | ns |
| | | | p-ch | | 44 | | ns |
| Q_{rr} | Reverse recovery charge | P-channel $I_{SD} = 3\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 20\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 27) | n-ch | | 85 | | nC |
| | | | p-ch | | 68.2 | | nC |
| I_{RRM} | Reverse recovery current | | n-ch | | 2 | | A |
| | | | p-ch | | 3.1 | | A |

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating n-ch

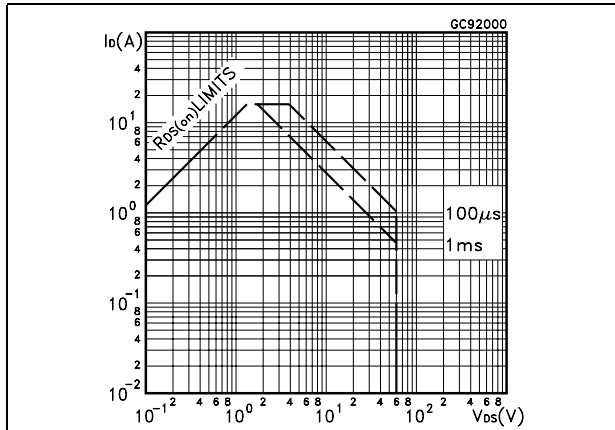


Figure 2. Thermal impedance for complementary pair

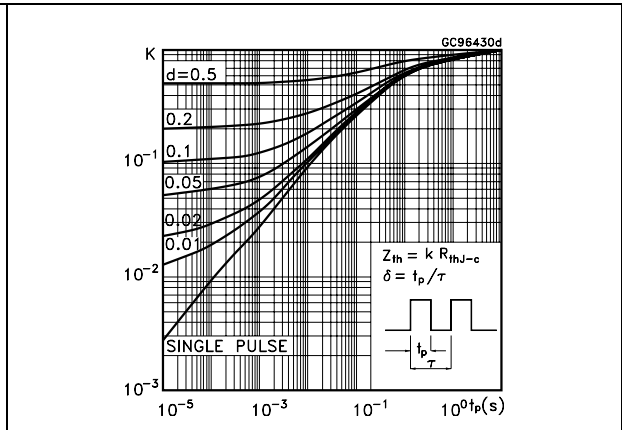


Figure 3. Output characteristics n-ch

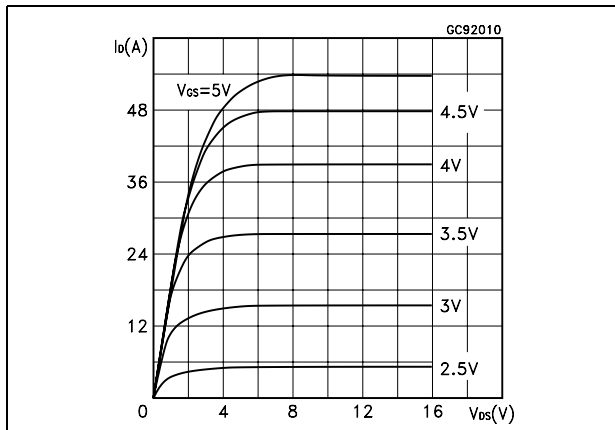


Figure 4. Transfer characteristics n-ch

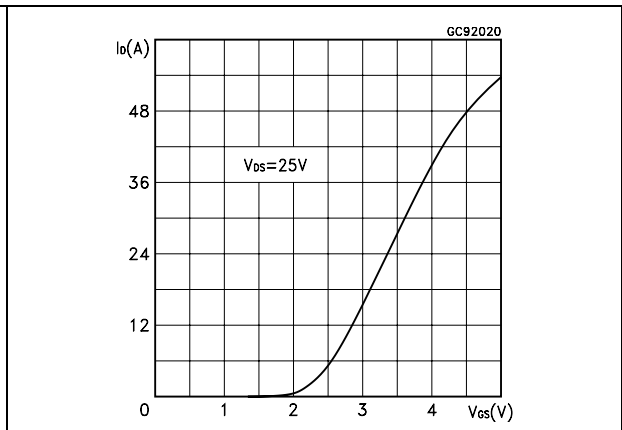


Figure 5. Transconductance n-ch

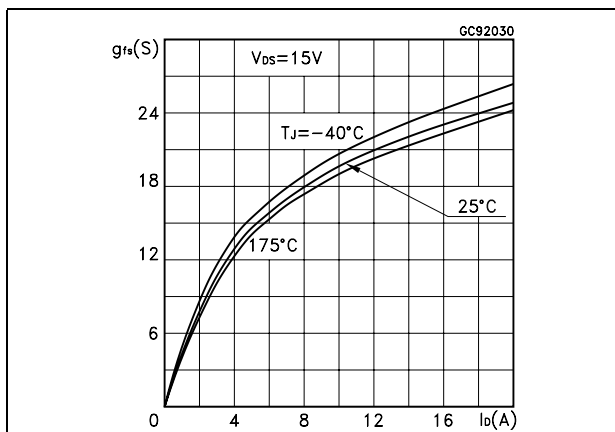


Figure 6. Static drain-source on resistance n-ch

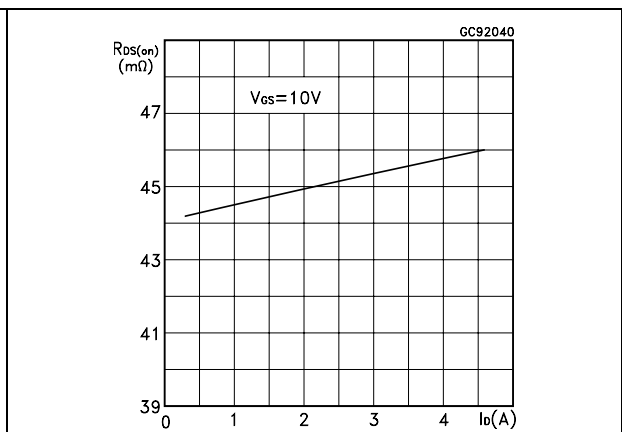


Figure 7. Gate charge vs. gate-source voltage Figure 8. Capacitance variations n-ch n-ch

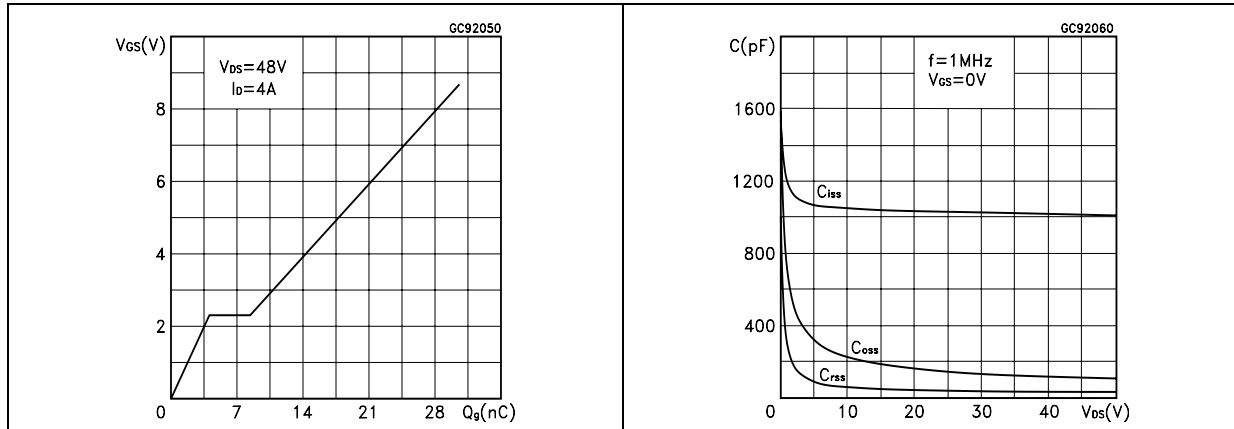


Figure 9. Normalized gate threshold voltage vs. temperature n-ch Figure 10. Normalized on resistance vs. temperature n-ch

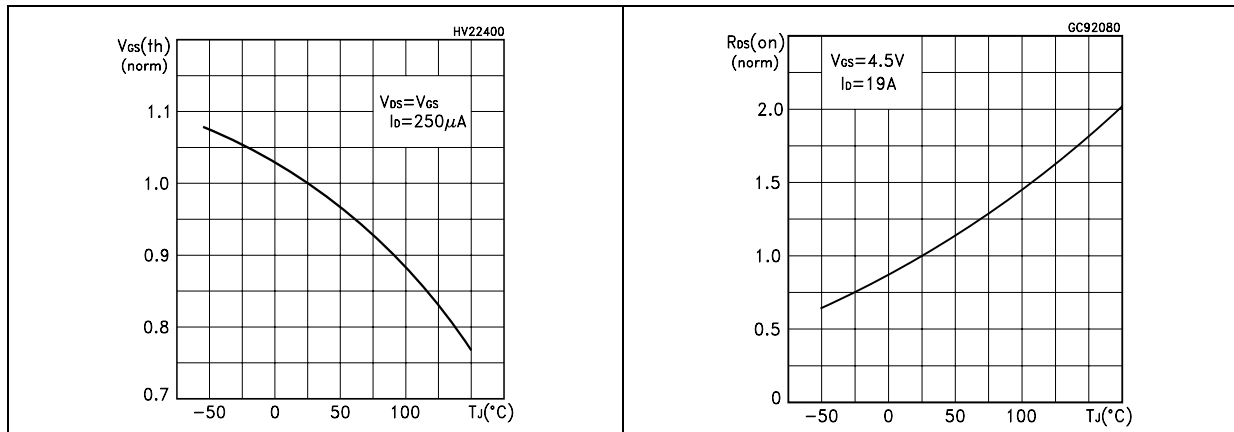


Figure 11. Source-drain diode forward characteristics n-ch Figure 12. Normalized breakdown voltage vs. temperature n-ch

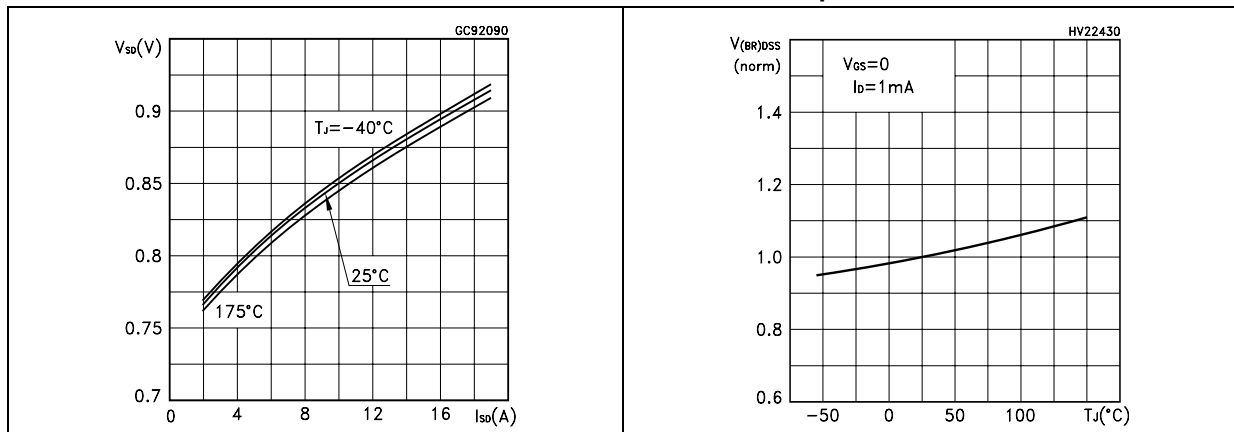


Figure 13. Safe operating p-ch

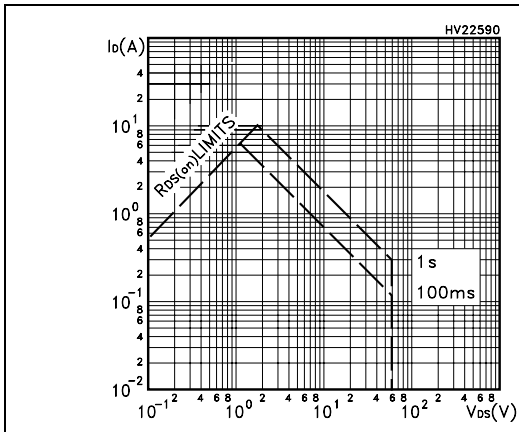


Figure 14. Thermal impedance p-ch

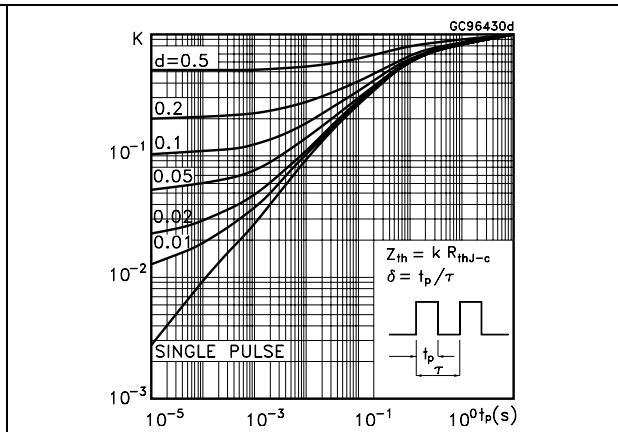


Figure 15. Output characteristics p-ch

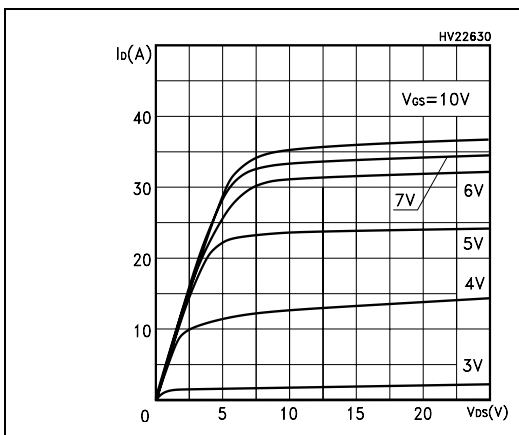


Figure 16. Transfer characteristics p-ch

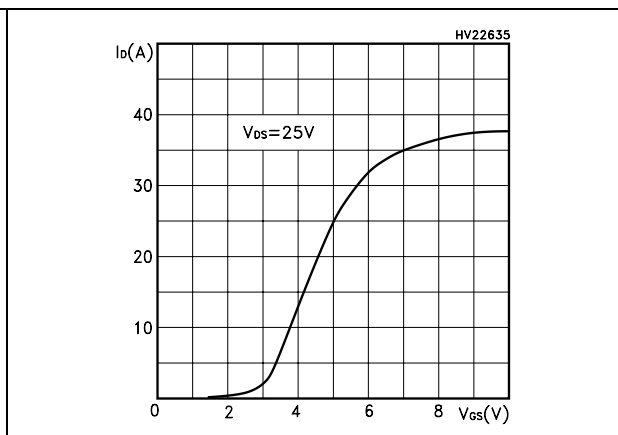


Figure 17. Transconductance p-ch

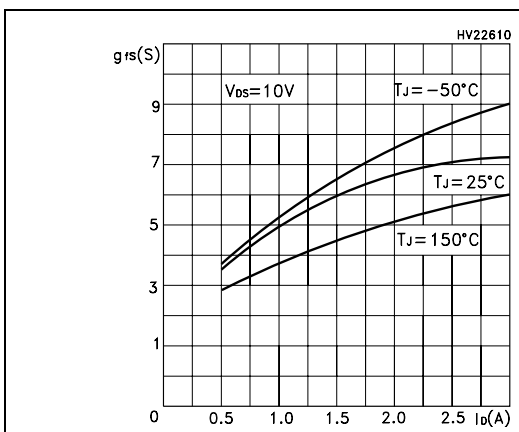


Figure 18. Static drain-source on resistance p-ch

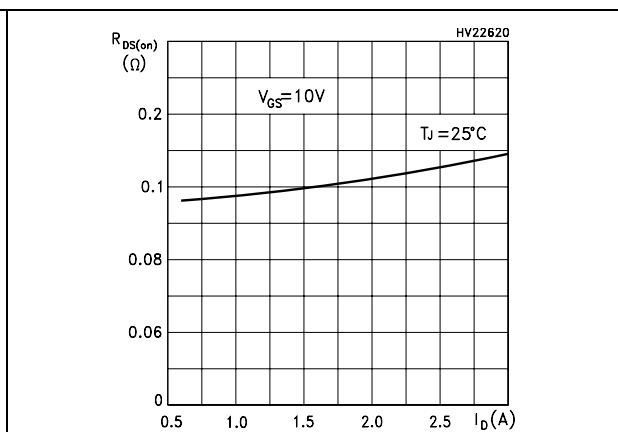


Figure 19. Gate charge vs. gate-source voltage Figure 20. Capacitance variations p-ch

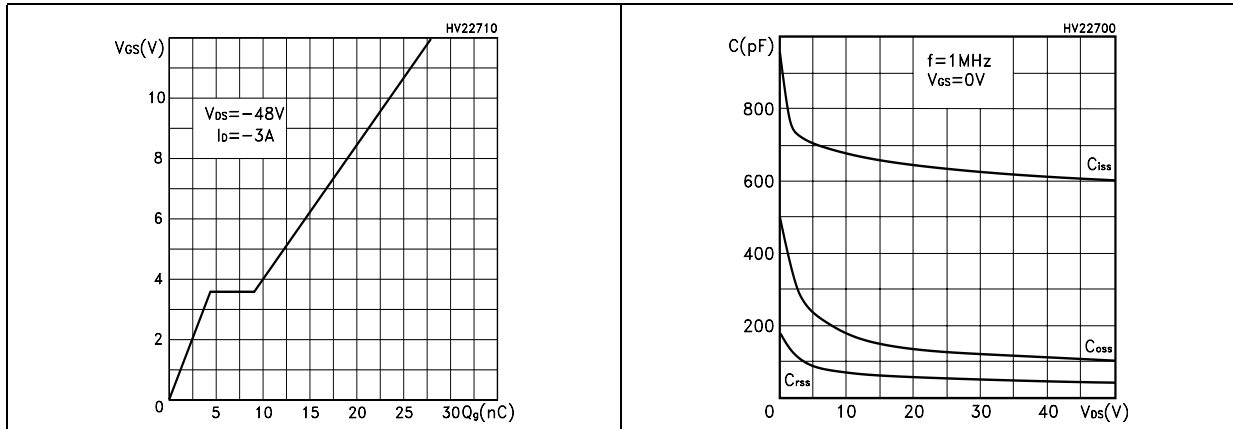


Figure 21. Normalized gate threshold voltage vs. temperature p-ch Figure 22. Normalized on resistance vs. temperature p-ch

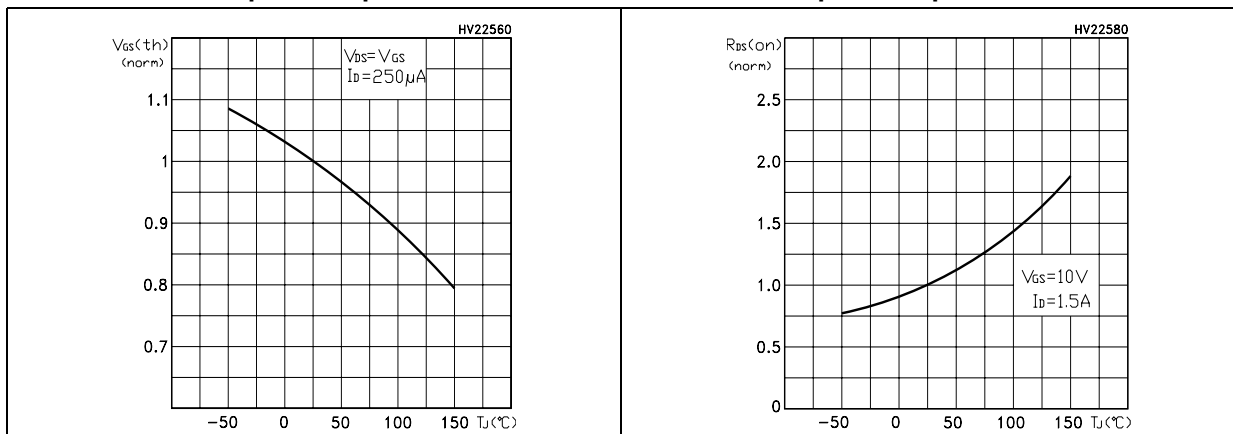
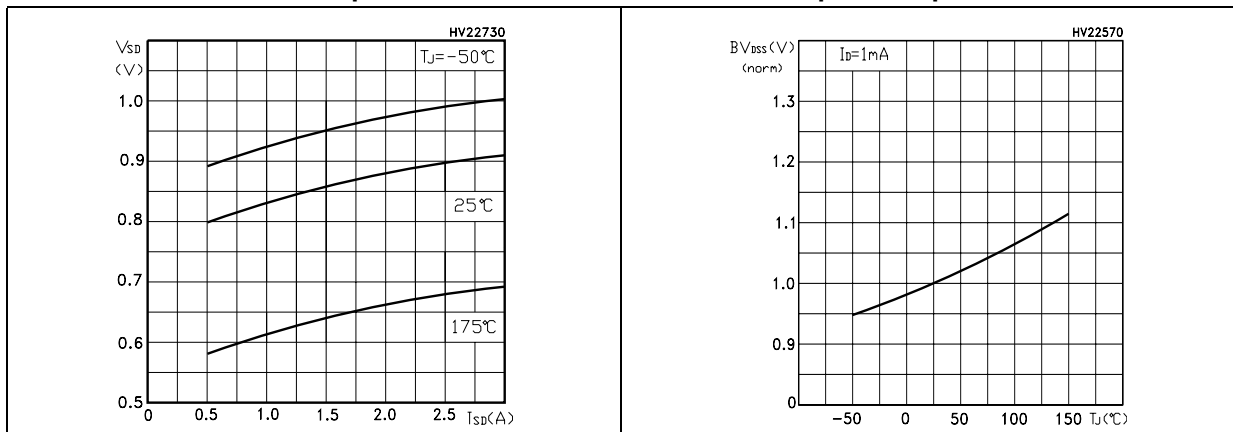


Figure 23. Source-drain diode forward characteristics p-ch Figure 24. Normalized breakdown voltage vs. temperature p-ch



3 Test circuit

Figure 25. Switching times test circuit for resistive load

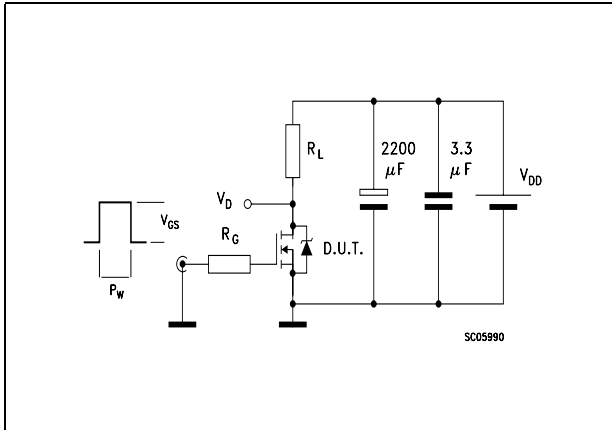


Figure 26. Gate charge test circuit

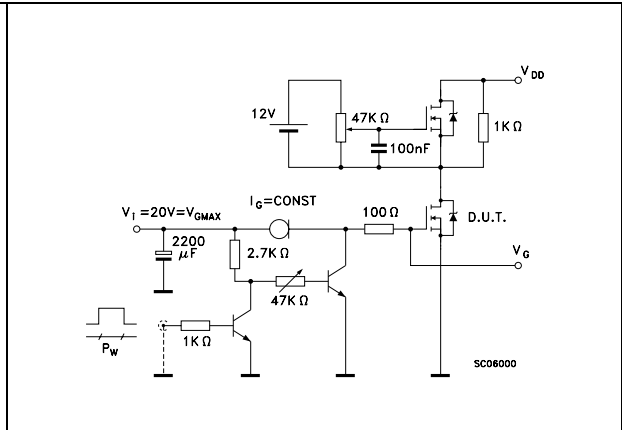


Figure 27. Test circuit for inductive load switching and diode recovery times

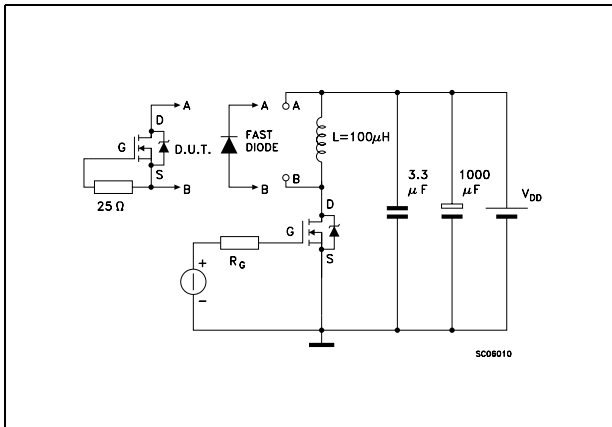


Figure 28. Unclamped Inductive load test circuit

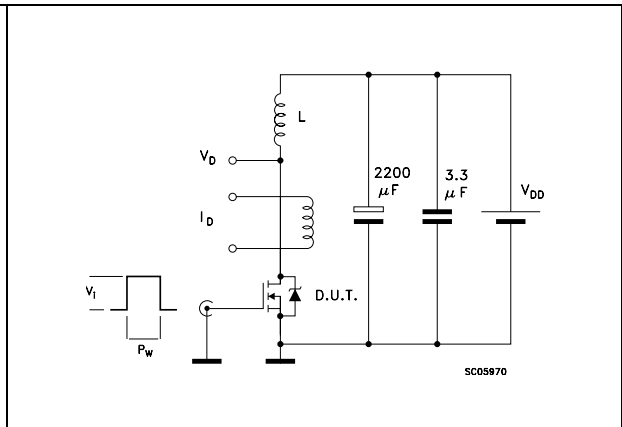


Figure 29. Unclamped inductive waveform

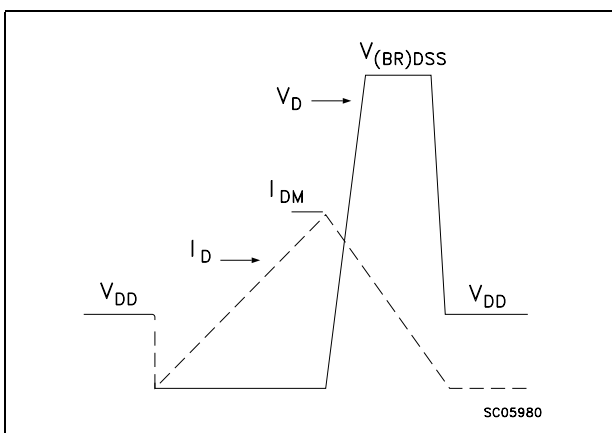
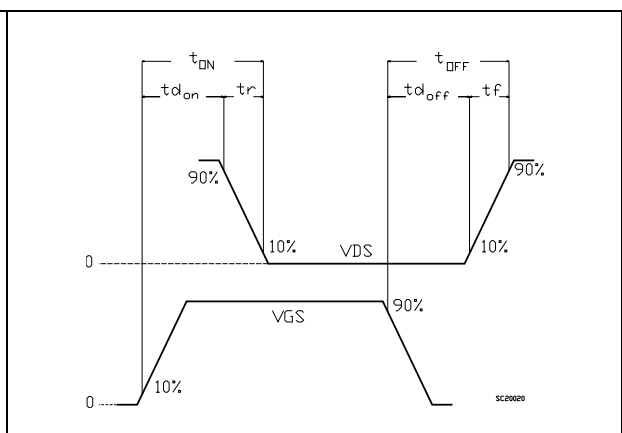


Figure 30. Switching time waveform

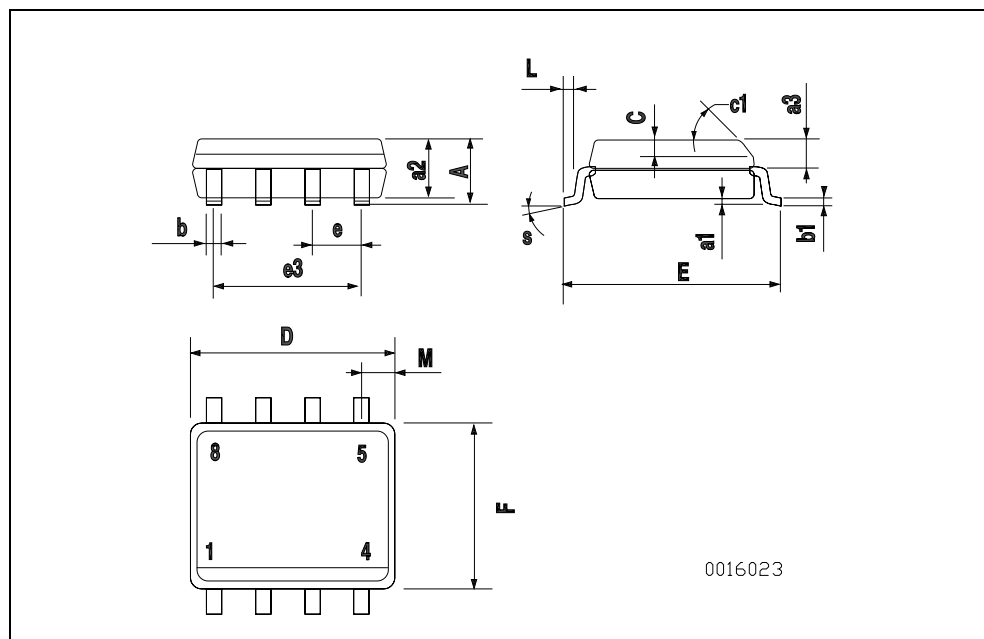


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at : www.st.com

SO-8 MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|-----------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | | | 1.75 | | | 0.068 |
| a1 | 0.1 | | 0.25 | 0.003 | | 0.009 |
| a2 | | | 1.65 | | | 0.064 |
| a3 | 0.65 | | 0.85 | 0.025 | | 0.033 |
| b | 0.35 | | 0.48 | 0.013 | | 0.018 |
| b1 | 0.19 | | 0.25 | 0.007 | | 0.010 |
| C | 0.25 | | 0.5 | 0.010 | | 0.019 |
| c1 | 45 (typ.) | | | | | |
| D | 4.8 | | 5.0 | 0.188 | | 0.196 |
| E | 5.8 | | 6.2 | 0.228 | | 0.244 |
| e | | 1.27 | | | 0.050 | |
| e3 | | 3.81 | | | 0.150 | |
| F | 3.8 | | 4.0 | 0.14 | | 0.157 |
| L | 0.4 | | 1.27 | 0.015 | | 0.050 |
| M | | | 0.6 | | | 0.023 |
| S | 8 (max.) | | | | | |



5 Revision history

Table 7. Revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 28-Sep-2004 | 1 | First release |
| 13-Nov-2006 | 2 | The document has been reformatted |
| 26-Jan-2007 | 3 | Typo mistake on Table 1 . |

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